

Specifications:

Material And Finish:

Dvi Housing:PBT,UL94V-0,Color: Black or White

Dvi Cover:LCP,UL94V-0,Color:Black or White.

Contact:Copper Alloy,Gold flash in contact area,

Tin plated in solder area,Nickel under plated over all

Shell: SPCC,Nickel plated over copper under plated over all

Board lock: SPCC, Tin plated over Nickel under plated over all.

Bracket: SPCC, Nickel plated over Copper under plated over all.

Semi Shield:Sus Non-plated

Rivet: Copper alloy, Nickel plated over Copper under plated over all

Crew: Steel, Nickel plated over Copper under plated over all

Rating:

Current Rating:1.5 Amp

Voltage Rating:250V AC/DC

Operating Temperature Range:-20'~+85'C

Electrical:

Contact resistance:Up port 30m Ohm Max

Lower port 20m Ohm Max

Insulator resistance:100M ohm min.at DC 500V

Withstanding Voltage:500V AC/Minute

Resistance to Soldering Heat: 265'C for 5s

Only applicable to wave soldering process

Mating force: 4.5kgf max

Unmating force: 1.0~4.0kgf

Ordering Information

DB106R-58XF-01-X

1 2 3 4 5 6

1: Series No.

2: R/R/A Type

3: No. of Positions

4: H:Gold flash on contact;

Matte Tin on tail

A1:Gold flash on contact;

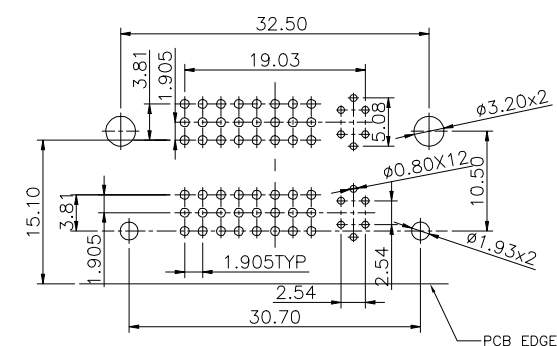
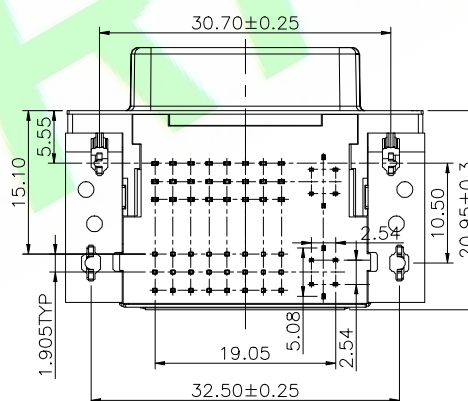
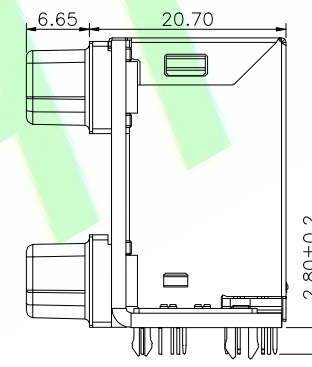
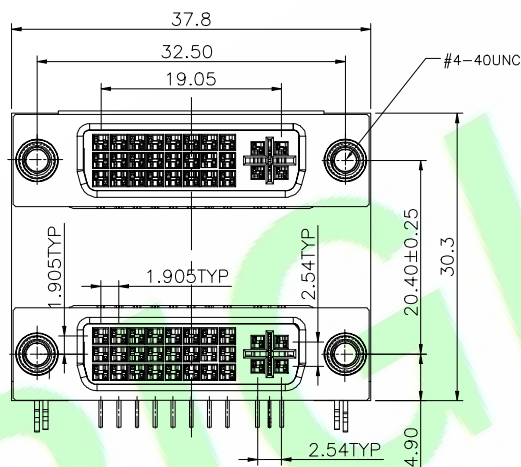
Tin on tail

5: F:Female

6: A:In Bag

B:In Tube

C:In Tray

RECOMMENDED P.C.B LAYOUT(PCB THICKNESS:1.6mm)
TOP VIEW

1X	ORIGNINAL	Bin	
REV.	DESCRIPTION	DR.BY	ECN. NO.

DR.BY.: Bin	GENERAL TOLERANCE:		PART NO : DB106R-58XF-01-X
	LINEAR	ANGLES	
CHKD.: Judyyan	X.: ±0.38	X': ±2.0°	DWG. NO.:
	X.X: ±0.35	X.X': ±1.0°	
APPD.: Billy	X.XX: ±0.25	X.XX': ±0.5°	TITLE : DVI 24+5 Bouble-layer Riveting Tape Shielding H-20.4
	X.XXX: ±0.15	X.XXX': ±0.1°	
			DATE: 26-Dec-2023

HJBRIGHT® 东莞市華晶电子有限公司
BRIGHT-E TECHNOLOGY ELECTRONIC LIMITED

SHEET: 1/1

SCALE: 1:1

UNIT: mm



THIRD ANGLE PROJECTION

A4